

D1
End wherein the plurality of solder bumps bond the optical device substrate to the device bonding surface with the one or more optical devices aligned with the one or more optical lenses.

D2 5. (Amended) The optoelectronic device of claim 4, wherein a wafer bond bonds the optical substrate to the spacer substrate.

6. (Amended) The optoelectronic device of claim 4, wherein a solder bond bonds the optical substrate to the spacer substrate.

D3 10. (Amended) The optoelectronic device of claim 4, further comprising an integrated circuit bonded to the spacer substrate by a flip-chip solder bond and configured to drive the one or more optical devices.

D4 25. (Amended) The optoelectronic device of claim 13, wherein each of the spacer substrate apertures has a lens substrate opening at a surface facing the lens substrate and a device substrate opening at a surface facing the device substrate, wherein for each spacer substrate aperture the lens substrate opening is larger than the device substrate opening.

Please add the following new claims.

D5 31. The optoelectronic device of claim 4, wherein a wafer bond bonds the optical substrate to the spacer substrate.

32. The optoelectronic device of claim 4, wherein a solder bond bonds the optical substrate to the spacer substrate.

33. The optoelectronic device of claim 8, wherein each of the spacer substrate apertures has a lens substrate opening at a surface facing the lens substrate and a device substrate opening at a surface facing the device substrate, wherein for each spacer substrate aperture the lens substrate opening is larger than the device substrate opening.
